



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

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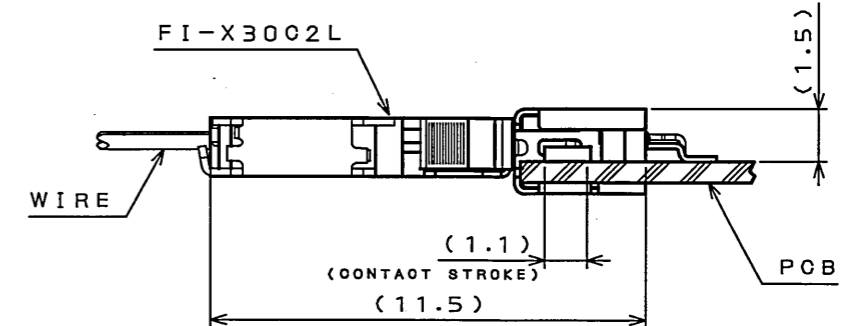
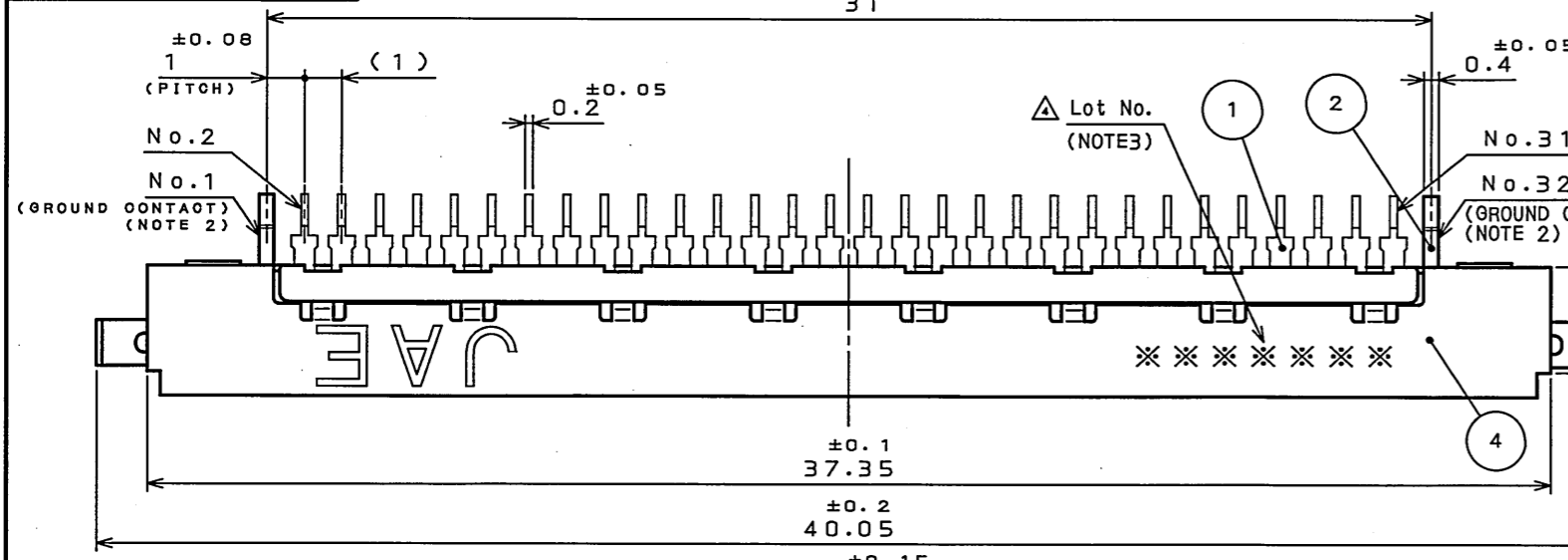
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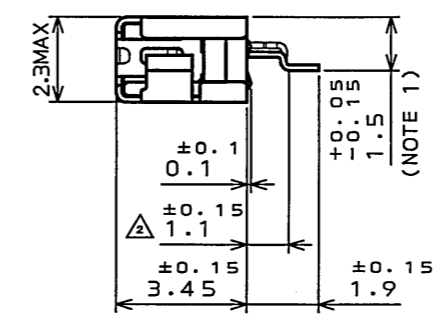
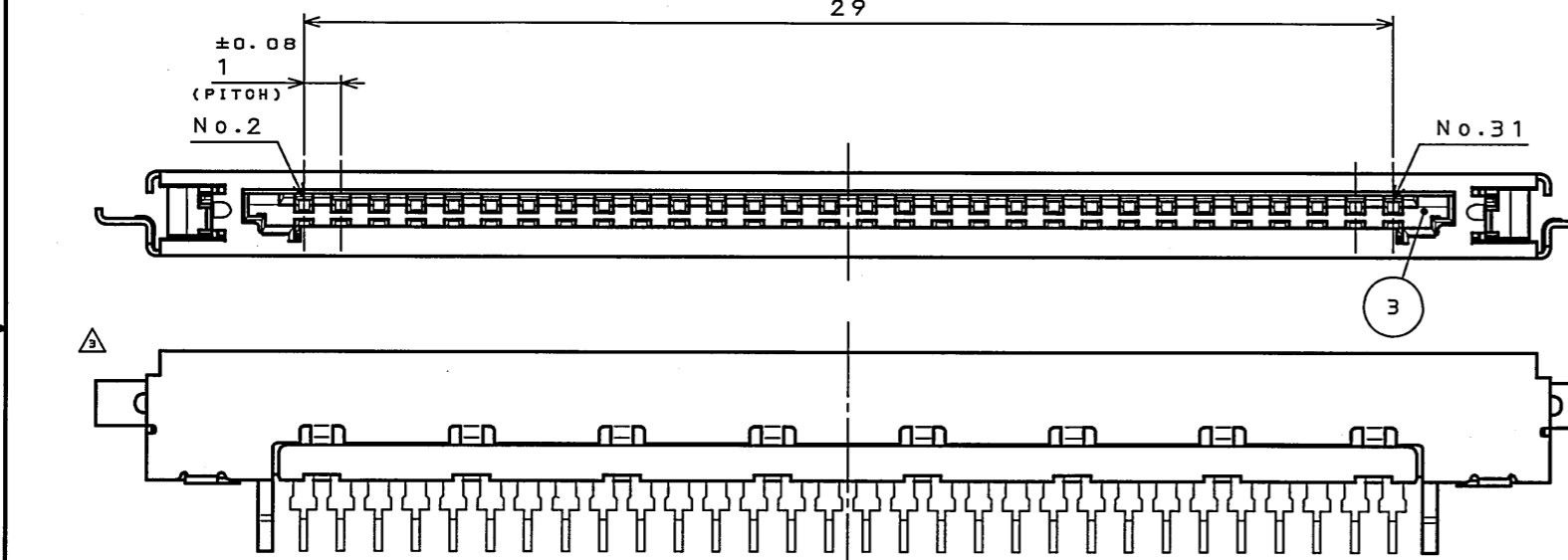


△JE8E01S  
(ON 0N1MAYH)各機理図

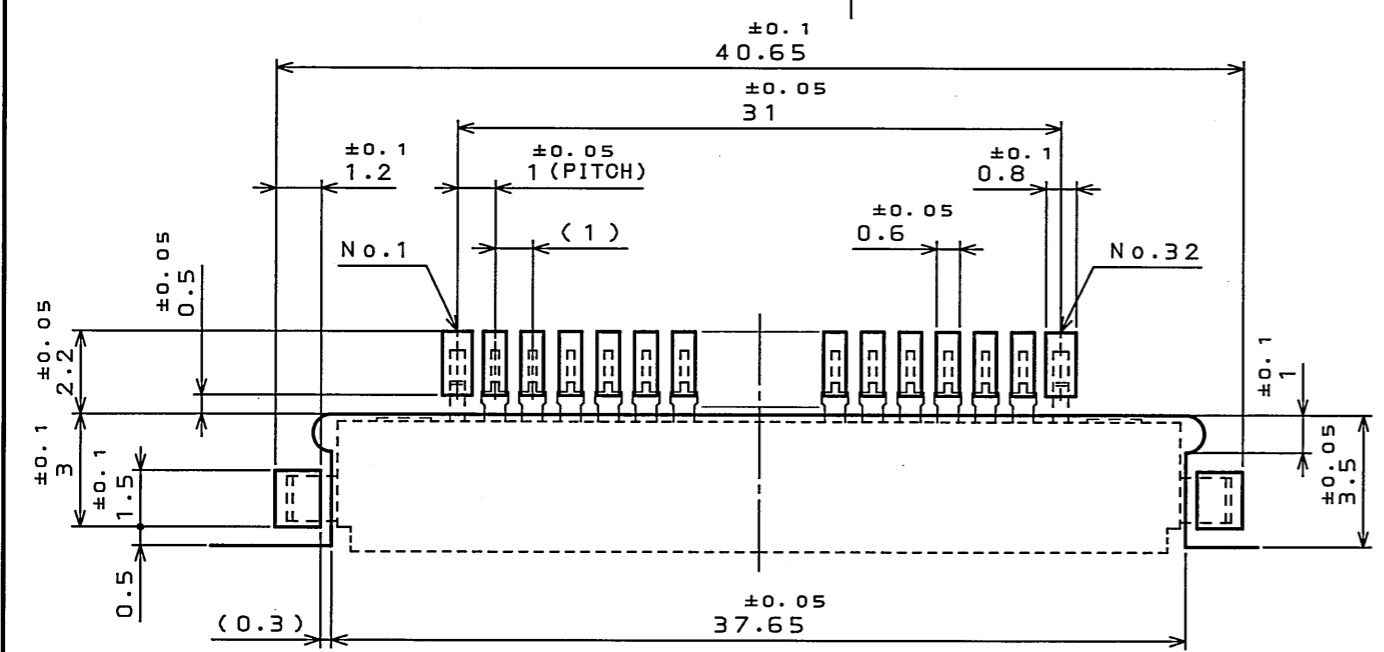
版数 REV.	年月日 DATE	DCN NO.	変更内容 DESCRIPTION	製図 DR.	担当 CHK.	査閲 APPD.	承認 APPD.
2	21.May.2003	52152	ADDED DIMENSIN 寸法追加	T.YAMAJI	K.HISAMATSU	A.KIMURA	Y.ICHIYAMA
3	14.Jul.2003	52482	ADDED FORM 下面図追加	—	K.HISAMATSU	—	Y.ICHIYAMA
4	3.Aug.2006	060641	ADDED LOT NO.& NOTE ロットNo.、注記追加	H.SAKURADA	T.SHIOIDA	m.Suzuki	K.Hisatomi



MATED CONDITION (REF.)  
嵌合状態図(参考)



- NOTE1. COPLANARITY BETWEEN TERMINAL AND HOLD DOWN OF SHELL SHOULD BE 0.08mm MAX.  
 2. TERMINALS NO.1 AND NO.32 ARE APPROPRIATE FOR GROUND CONTACTS.  
 △ 3. PRODUCTION LOT NUMBER AS INDICATED.  
 注1. 端子及び、シェルのホールドダウンの相互のパラツキは0.08以内である。  
 2. 端子No. 1, 32はグラウンド専用コンタクトとする。  
 △ 3. 図示の位置にロット番号を表示する。



APPLICABLE P.C.B. DIMENSION (REF.)  
適合基板寸法(参考)

符号 NO.	名称 DESCRIPTION	個数 QTY.	材料 MATERIAL	仕上 FINISH	備考 REMARKS
4	SHELL	1	STAINLESS STEEL	TIN PLATING	
3	INSULATOR	1	HEAT RESISTING PLASTIC		UL94 V-0 BEIGE
2	GROUND PLATE	1	COPPER ALLOY	TIN PLATING	
1	CONTACT	30	COPPER ALLOY	GOLD(0.1μmMIN) OVER NICKEL	TERMINAL AREA: TIN-COPPER OVER NICKEL

仕様書(SPECIFICATION)	第1版(ORIGINAL DATE) 4.Mar.2003	尺度(SCALE) 5:1	シリーズ(SERIES) FI-X
製図 DR.	T.YAMAJI	名称(TITLE) FI-XB30SSL-HF15 (PCB SIDE)	
担当 CHK.	K.HISAMATSU	質量(MASS)	
査閲 APPD.	A.KIMURA	製図 DR.	
承認 APPD.	Y.ICHIYAMA	承認 APPD.	

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